

IGBT Module**Sixpack**

Short Circuit SOA Capability

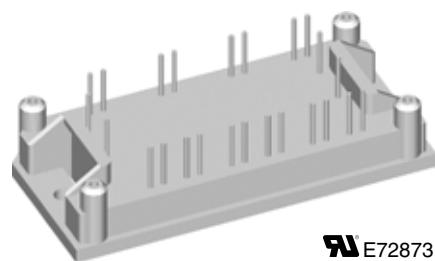
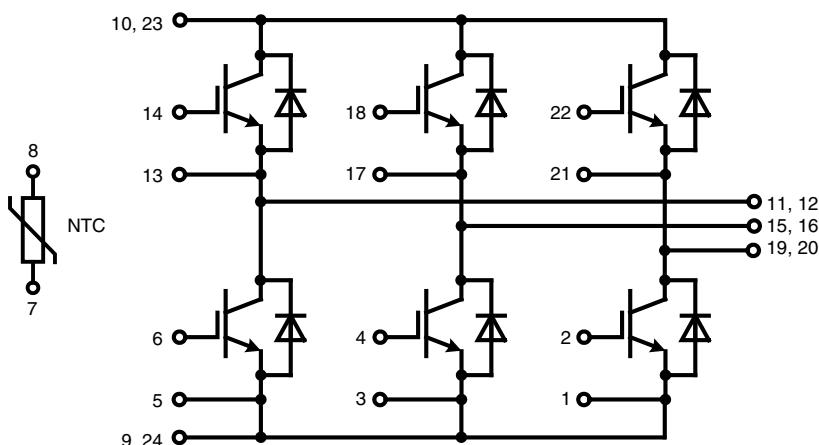
Square RBSOA

 I_{C25} = 80 A
 V_{CES} = 1200 V
 $V_{CE(sat)\ typ.}$ = 2.0 V

Preliminary data

Part name (Marking on product)

MWI 80-12T6K



E72873

Pin configuration see outlines.

Features:

- Trench IGBTs
 - low saturation voltage
 - positive temperature coefficient for easy paralleling
 - fast switching
 - short tail current for optimized performance also in resonant circuits
- HiPerFRED™ diode:
 - fast reverse recovery
 - low operating forward voltage
 - low leakage current
- Industry Standard Package
 - solderable pins for PCB mounting
 - isolated copper base plate

Application:

- AC drives
- UPS
- Welding

Package:

- UL registered
- Industry standard E1-pack

IGBTs

Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ\text{C}$ to 150°C		1200		V
V_{GES}	max. DC gate voltage	continuous		± 20		V
V_{GEM}	max. transient collector gate voltage	transient		± 30		V
I_{C25}	collector current	$T_C = 25^\circ\text{C}$	80			A
I_{C80}		$T_C = 80^\circ\text{C}$	56			A
P_{tot}	total power dissipation	$T_C = 25^\circ\text{C}$	270			W
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 50 \text{ A}; V_{GE} = 15 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	2.0 2.3	2.4	V
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 2 \text{ mA}; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ\text{C}$	4.5	6.5	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		1 0.8	mA mA
I_{GES}	gate emitter leakage current	$V_{CE} = 0 \text{ V}; V_{GE} = \pm 20 \text{ V}$			400	nA
C_{ies}	input capacitance	$V_{CE} = 25 \text{ V}; V_{GE} = 0 \text{ V}; f = 1 \text{ MHz}$		3600		pF
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 \text{ V}; V_{GE} = 15 \text{ V}; I_C = 50 \text{ A}$		470		nC
$t_{d(on)}$	turn-on delay time	$T_{VJ} = 125^\circ\text{C}$	90			ns
t_r	current rise time		50			ns
$t_{d(off)}$	turn-off delay time		520			ns
t_f	current fall time		90			ns
E_{on}	turn-on energy per pulse		5			mJ
E_{off}	turn-off energy per pulse		6.5			mJ
I_{CM}	reverse bias safe operating area	$RBSOA; V_{GE} = \pm 15 \text{ V}; R_G = 18 \Omega$ $L = 100 \mu\text{H}; \text{clamped induct. load}$ $V_{CEmax} = V_{CES} - L_s \cdot di/dt$	$T_{VJ} = 125^\circ\text{C}$	100		A
t_{sc} (SCSOA)	short circuit safe operating area	$V_{CE} = 900 \text{ V}; V_{GE} = \pm 15 \text{ V}; R_G = 18 \Omega; \text{non-repetitive}$	$T_{VJ} = 125^\circ\text{C}$	10		μs
R_{thJC}	thermal resistance junction to case	(per IGBT)			0.46	K/W
R_{thCH}	thermal resistance case to heatsink	(per IGBT)		0.2		K/W

Diodes

Maximum Ratings

Symbol	Definitions	Conditions	Maximum Ratings
V_{RRM}	max. repetitive reverse voltage		1200 V
I_{F25}	forward current	$T_C = 25^\circ\text{C}$	80 A
I_{F80}		$T_C = 80^\circ\text{C}$	51 A

Symbol Conditions

Characteristic Values

Symbol	Conditions	min.	typ.	max.		
V_F	forward voltage	$I_F = 50 \text{ A}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	2.3 1.6	2.6	V
I_{RM} t_{rr}	max. reverse recovery current reverse recovery time	$V_R = 600 \text{ V}; I_F = 50 \text{ A}$ $di_F/dt = -600 \text{ A}/\mu\text{s}$	$T_{VJ} = 100^\circ\text{C}$	35 200		A ns
R_{thJC}	thermal resistance junction to case	(per diode)	$T_{VJ} = 25^\circ\text{C}$		0.65	K/W
R_{thCH}	thermal resistance case to heatsink	(per diode)		0.25		K/W

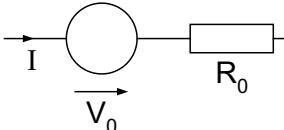
Temperature Sensor NTC

Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
R_{25}	<i>resistance</i>		$T_c = 25^\circ\text{C}$	4.45	4.7	5.0
$B_{25/85}$				3510		K

Module

Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
T_{VJ}	<i>operating temperature</i>		-40		125	°C
T_{VJM}	<i>max. virtual junction temperature</i>				150	°C
T_{stg}	<i>storage temperature</i>		-40		125	°C
V_{ISOL}	<i>isolation voltage</i>	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}$			2500	V~
M_d	<i>mounting torque</i>	(M4)	2.0		2.2	Nm
d_s	<i>creep distance on surface</i>		12.7			mm
d_A	<i>strike distance through air</i>		12.7			mm
Weight				40		g

Equivalent Circuits for Simulation

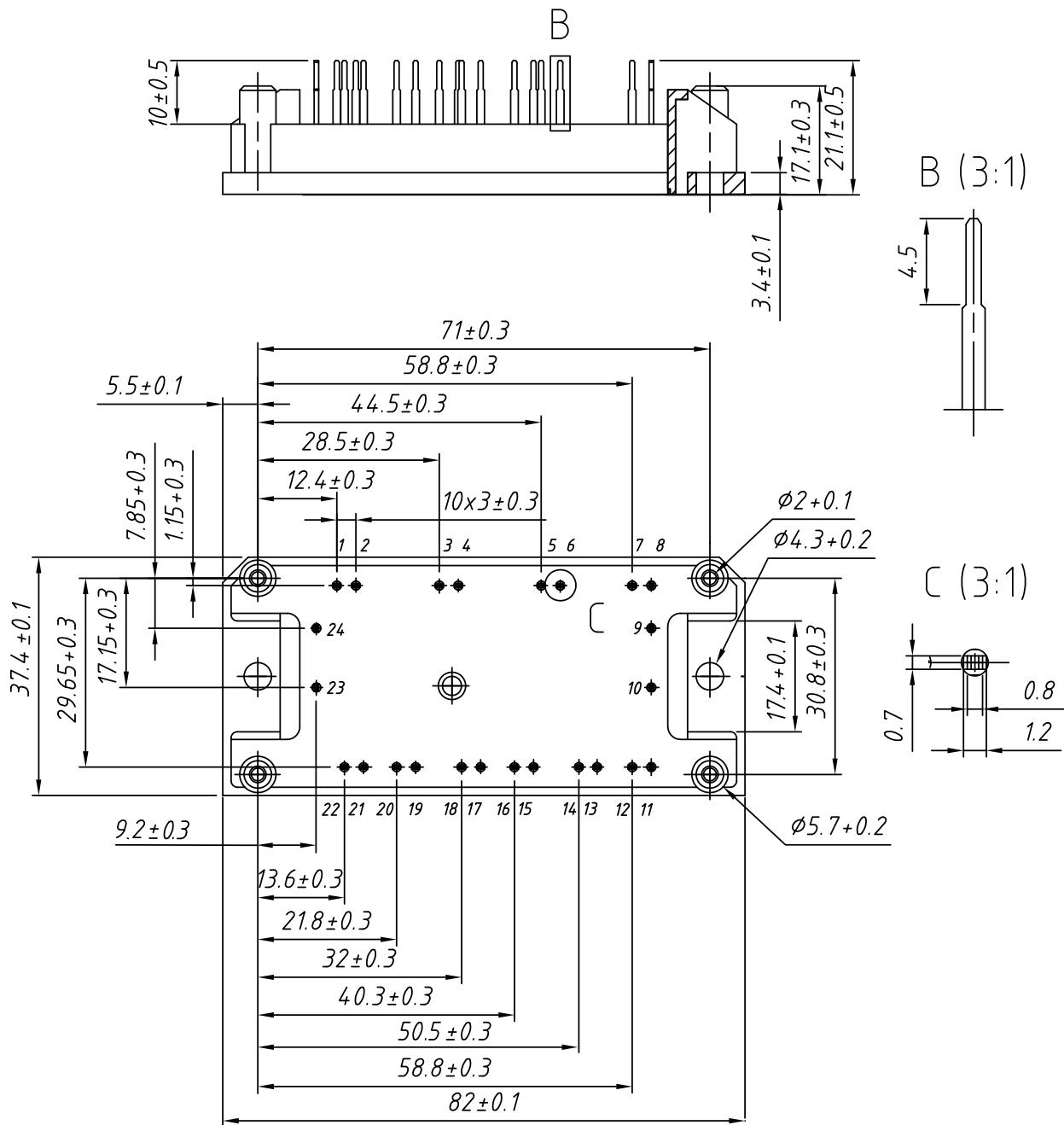


Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_0	<i>IGBT</i>	$T_{VJ} = 125^\circ\text{C}$		1.25		V
R_0				25		mΩ
V_0	<i>free wheeling diode</i>	$T_{VJ} = 125^\circ\text{C}$		1.5		V
R_0				6		mΩ

Outline Drawing

Dimensions in mm (1 mm = 0.0394")



Product Marking

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	MWI 80-12T6K	MWI80-12T6K	Box	10	500 159

IXYS reserves the right to change limits, test conditions and dimensions.

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